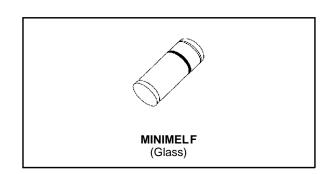


TMMBAR 19

SMALL SIGNAL SCHOTTKY DIODE



DESCRIPTION

Metal to silicon junction diode primarly intended for UHF mixers and ultrafast switching applications.

ABSOLUTE MAXIMUM RATINGS (limiting values)

Symbol	Parameter	Value	Unit
V_{RRM}	Repetitive Peak Reverse Voltage	4	V
I _F	Forward Continuous Current	30	mA
I _{FSM}	Surge non Repetitive Forward Current	60	mA
T _{stg} Tj	Storage and Junction Temperature Range	- 65 to +150 - 65 to +125	°C °C
TL	Maximum Temperature for Soldering during	260	°C

THERMAL RESISTANCE

Symbol	Test Conditions	Value	Unit
$R_{th(j-l)}$	Junction-leads	400	°C/W

ELECTRICAL CHARACTERISTICS

STATIC CHARACTERISTICS

Symbol	Test Conditions			Min.	Тур.	Max.	Unit
V _{BR}	T _{amb} = 25°C	$I_R = 10\mu A$		4			V
V _F (1)	T _{amb} = 25°C	$I_F = 10mA$				0.6	V
I _R (1)	T _{amb} = 25°C	$V_R = 3V$				0.25	μΑ

DYNAMIC CHARACTERISTICS

Symbol	Test Conditions			Min.	Тур.	Max.	Unit
С	T _{amb} = 25°C	$V_R = 1V$	f = 1MHz			1	pF
F (2)	T _{amb} = 25°C	f = 1GHz			6		dB

⁽¹⁾ Pulse test: $t_p \le 300 \mu s \ \delta < 2\%$.

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⁽²⁾ Noise figure test :

⁻ diode is inserted in a tuned stripline circuit

⁻ local oscillator frequency 1GHz

⁻ local oscillator power 1mW

⁻ intermediate frequency amplifier, tuned on 30MHz, has a noise figure 1.5dB

Figure 1. Forward current versus forward voltage (typical values).

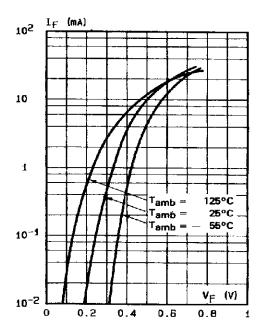


Figure 2. Capacitance C versus reverse applied voltage $V_{\mbox{\scriptsize R}}$ (typical values).

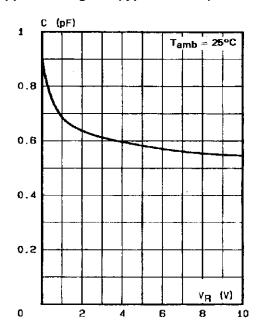


Figure 3. Reverse current versus ambient temperature.

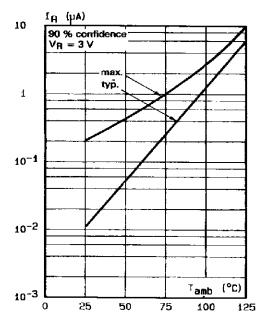
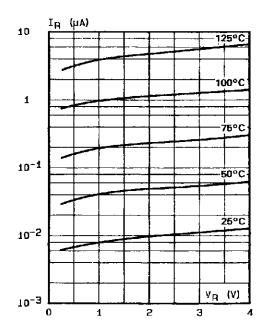


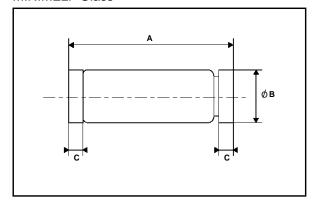
Figure 4. Reverse current versus continuous reverse voltage (typical values).

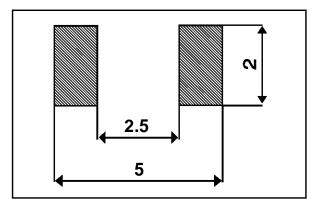


PACKAGE MECHANICAL DATA

FOOT PRINT DIMENSIONS (Millimeter)

MINIMELF Glass





	DIMENSIONS					
REF.	Millin	neters	Inches			
	Min.	Max.	Min.	Max.		
Α	3.3	3.6	0.130	0.142		
В	1.59	1.62	0.063	0.064		
С	0.4	0.5	0.016	0.020		

Marking: ring at cathode end. Weight: 0.05g

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